

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An optical module comprising a die pad, at least two platform bodies including a first platform body and a second platform body mounted on the die pad, an optical fiber fixed on the first platform body, and a light emitter mounted on the second platform body and adapted for generating optical signals ~~to which should~~ be transmitted through the optical fiber.

2. (Currently Amended) An optical module in accordance with Claim 1, which further comprises a receiving photo-diode mounted on the first platform body and adapted for transforming optical signals received through the optical fiber into electric signals, and a filter provided so that the optical fiber is divided at the position between the receiving photo-diode and the light emitter. ~~The optical module further comprises a ferrule in which the end portion of the optical fiber is inserted.~~

3. (Currently Amended) An optical module in accordance with Claim ~~1 or 2,~~ 1, which further comprises a ferrule in which the end portion of the optical fiber is inserted.

4. (Currently Amended) An optical module in accordance with ~~any one of Claims 1 to 3,~~ Claim 2, which further comprises a ~~monitoring photo-diode~~ferrule ~~in which is mounted on the second platform body and used for monitoring the luminescence intensity of the light emitter~~the end portion of the optical fiber is inserted.

5. (Currently Amended) An optical module in accordance with ~~any one of Claims 1 to 4,~~ Claim 2, which further comprises ~~an encapsulation member which covers at least part of the first platform body and~~ a monitoring photo-diode which is mounted on the second platform body and ~~part used for monitoring the luminescence intensity of the die pad~~ light emitter.

6. (Currently Amended) An optical module in accordance with Claim 5, ~~wherein the first platform body and the second platform body are arranged on the die pad in parallel with each other.~~ 4, which further comprises a monitoring photo-diode which is mounted on the second platform body and used for monitoring the luminescence intensity of the light emitter.

7. (Currently Amended) An optical module in accordance with Claim 5, ~~wherein~~ which further comprises an encapsulation member which covers at least part of the first platform body is placed on and ~~the second platform body; and part of the die pad~~

8. (Currently Amended) An optical module in accordance with ~~any one of Claims 1 to 7,~~ Claim 6, which further comprises ~~silicone gel~~ an encapsulation member which covers at least part of the ~~optical fiber, the receiving photo-diode, the light emitter or the filter.~~ first platform body and the second platform body and part of the die pad

9. (Currently Amended) An optical module in accordance with ~~any one of Claims 1 to 8,~~ which further comprises ~~at least one IC which receive the output signals from the receiving photo-diode and process the output signals and/or drive the~~

~~light emitter.~~ Claim 7, wherein the first platform body and the second platform body are arranged on the die pad in parallel with each other.

10. (Currently Amended) An optical module in accordance with Claim 9, ~~8~~, wherein the ~~at least one IC may be mounted on the first platform body or~~ and the second platform body are arranged on the die pad in parallel with each other.

11. (Currently Amended) An optical module in accordance with Claim 9, ~~7~~, wherein the ~~at least one IC may be mounted on the die pad~~ first platform body is placed on the second platform body.

12. (Currently Amended) An optical module in accordance with ~~any one of Claims 1 to 11, which further comprises a plurality of leads at least a part of which is covered by the encapsulation member.~~ Claim 8, wherein the first platform body is placed on the second platform body.

13. (Currently Amended) An optical module in accordance with Claim ~~12, wherein the plurality of leads are drawn out from a package body consisting of the encapsulation member.~~ 2, which further comprises silicone gel which covers at least part of the optical fiber, the receiving photo-diode, the light emitter or the filter.

14. (Currently Amended) An optical module in accordance with Claim ~~12, wherein the plurality of leads terminated at a mounting surface consisting of the encapsulation member.~~ 5, which further comprises silicone gel which covers at least part of the optical fiber, the receiving photo-diode, the light emitter or the filter.

15. (Currently Amended) An optical module in accordance with ~~any one of Claims 1 to 14, wherein the die pad is located at a side opposite to a mounting surface of the package body with respect to the platform bodies~~ Claim 2, which further comprises at least one IC which receive the output signals from the receiving photo-diode and process the output signals and/or drive the light emitter.

16.-19. (Canceled)

20. (New) An optical module in accordance with Claim 5, which further comprises at least one IC which receive the output signals from the receiving photo-diode and process the output signals and/or drive the light emitter.

21. (New) An optical module in accordance with Claim 15, wherein the at least one IC may be mounted on the first platform body or the second platform body.

22. (New) An optical module in accordance with Claim 20, wherein the at least one IC may be mounted on the first platform body or the second platform body.

23. (New) An optical module in accordance with Claim 15, wherein the at least one IC may be mounted on the die pad.

24. (New) An optical module in accordance with Claim 20, wherein the at least one IC may be mounted on the die pad.

25. (New) An optical module in accordance with Claim 7, which further comprises a plurality of leads at least a part of which is covered by the encapsulation member.

26. (New) An optical module in accordance with Claim 8, which further comprises a plurality of leads at least a part of which is covered by the encapsulation member.

27. (New) An optical module in accordance with Claim 25, wherein the plurality of leads are drawn out from a package body consisting of the encapsulation member.

28. (New) An optical module in accordance with Claim 26, wherein the plurality of leads are drawn out from a package body consisting of the encapsulation member.

29. (New) An optical module in accordance with Claim 25, wherein the plurality of leads terminated at a mounting surface consisting of the encapsulation member.

30. (New) An optical module in accordance with Claim 26, wherein the plurality of leads terminated at a mounting surface consisting of the encapsulation member.

31. (New) An optical module in accordance with Claim 1, wherein the die pad is located at a side opposite to a mounting surface of the package body with respect to the platform bodies.

32 (New) An optical module in accordance with Claim 1, wherein the die pad is provided on a printed circuit board.

33. (New) A method of fabricating an optical module for transmitting and receiving optical signals comprising a step of mounting on a die pad a second platform body including at least a light emitter which generates optical signals to be transmitted, a step of mounting on the die pad or the second platform body a first platform body including at least optical fibers, a receiving photo-diode that performs photoelectric conversion of an optical signal received through the optical fibers and a filter that separates the optical signal received from the optical signal to be transmitted, and a step of encapsulating the second platform body and the first platform body with an encapsulation member so that end portions of the optical fibers opposite to the light emitter are exposed.

34. (New) A method of fabricating an optical module in accordance with Claim 35, which further comprises a step of mounting the second platform body on the die pad, a step of performing a screening test and mounting the first platform body on the die pad.

35. (New) A method of fabricating an optical module in accordance with Claim 33, which further comprises a step of applying silicon gel to cover at least part of the optical fiber, the receiving photo-diode, the light emitter or the filter.

36. (New) A method of fabricating an optical module in accordance with Claim 34, which further comprises a step of applying silicon gel to cover at least part of the optical fiber, the receiving photo-diode, the light emitter or the filter.